

# Silicon Carbide (SiC) Schottky Diode – EliteSiC, 10 A, 650 V, D2, TO-220-2L

# FFSP1065B-F085

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

### **Features**

- Max Junction Temperature 175°C
- Avalanche Rated 49 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

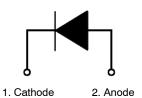
### **Applications**

- Automotive HEV-EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters

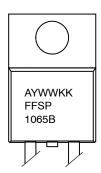


TO-220-2LD CASE 340BB

# **ELECTRICAL CONNECTION**



### MARKING DIAGRAM



YWW KK FFSP1065B = Assembly Plant Code= Date Code (Year & Week)= Lot Traceability Code

= Specific Device Code

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Symbol	Parameter			Unit
$V_{RRM}$	Peak Repetitive Reverse Voltage		650	V
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)			mJ
IF	Continuous Rectified Forward Current @ T <sub>C</sub> < 139°C			Α
	Continuous Rectified Forward Current @ T <sub>C</sub> < 135°C			
I <sub>F, Max</sub>	Non-Repetitive Peak Forward Surge Current	T <sub>C</sub> = 25°C, 10 μs	650	Α
		T <sub>C</sub> = 150°C, 10 μs	570	
I <sub>F, SM</sub>	Non-Repetitive Forward Surge Current	Half–Sine Pulse, $t_p = 8.3 \text{ ms}$	45	Α
P <sub>tot</sub>	Power Dissipation	T <sub>C</sub> = 25°C	75	W
		T <sub>C</sub> = 150°C	12.5	
$T_J$ , $T_{STG}$	Operating and Storage Temperature Range		-55 to +175	°C

<sup>1.</sup>  $E_{AS}$  of 49 mJ is based on starting  $T_J$  = 25°C, L = 0.5 mH,  $I_{AS}$  = 14 A, V = 50 V.

# THERMAL CHARACTERISTICS

Sy	ymbol	Parameter	Ratings	Unit
F	$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	2.0	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 10 A, T <sub>C</sub> = 25°C	-	1.38	1.7	V
		I <sub>F</sub> = 10 A, T <sub>C</sub> = 125°C	-	1.6	2.0	
		I <sub>F</sub> = 10 A, T <sub>C</sub> = 175°C	-	1.72	2.4	
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 650 V, T <sub>C</sub> = 25°C	-	0.5	40	μΑ
		V <sub>R</sub> = 650 V, T <sub>C</sub> = 125°C	-	1.0	80	
		$V_R = 650 \text{ V}, T_C = 175^{\circ}\text{C}$	-	2.0	160	
$Q_{\mathbb{C}}$	Total Capacitive Charge	V = 400 V	-	25	-	nC
С	Total Capacitance	V <sub>R</sub> = 1 V, f = 100 kHz	-	421	-	pF
		V <sub>R</sub> = 200 V, f = 100 kHz	-	46	-	
		V <sub>R</sub> = 400 V, f = 100 kHz	-	35	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FFSP1065B-F085	FFSP1065B	TO-220-2L	Tube	N/A	N/A	50 Units

# TYPICAL CHARACTERISTICS TJ = 25°C UNLESS OTHERWISE NOTED

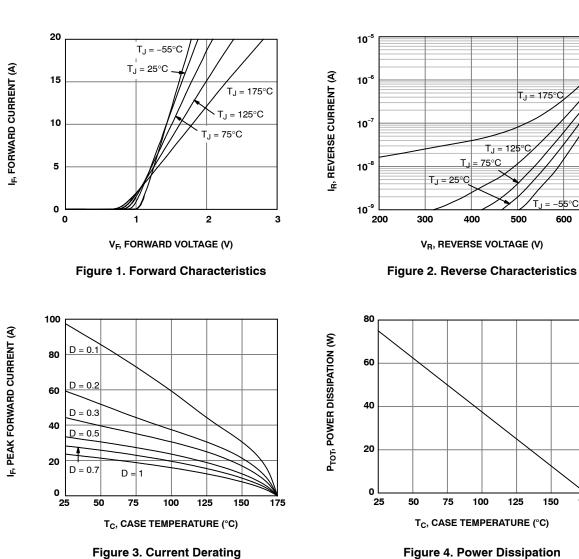


Figure 3. Current Derating

40

30

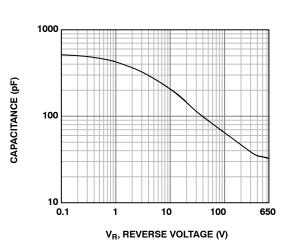
20

10

0

100

Q<sub>C</sub>, CAPACITANCE CHARGE (nC)



600 650

150

175

Figure 5. Capacitance Charge vs. Reverse Voltage

**V<sub>R</sub>, REVERSE VOLTAGE (V)** 

300

400

500

600 650

Figure 6. Capacitance vs. Reverse Voltage

# TYPICAL CHARACTERISTICS T<sub>J</sub> = 25°C UNLESS OTHERWISE NOTED (CONTINUED)

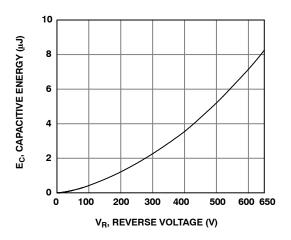


Figure 7. Capacitance Stored Energy

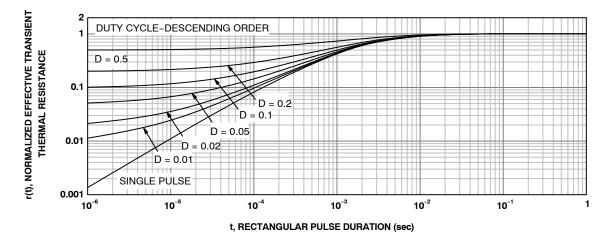


Figure 8. Junction-to-Case Transient Thermal Response Curve

# **TEST CIRCUIT AND WAVEFORMS**

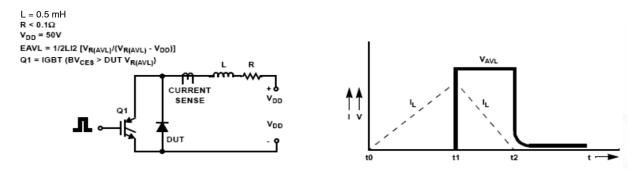
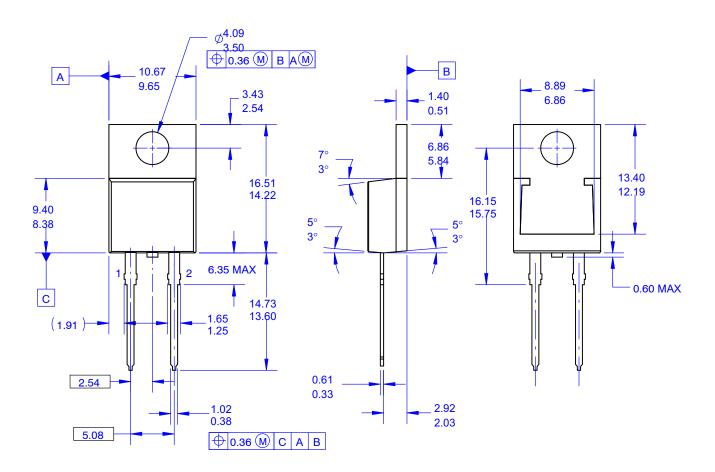
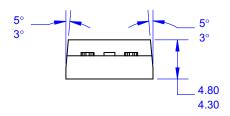


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

### **PACKAGE DIMENSIONS**

TO-220-2LD CASE 340BB **ISSUE O** 





# **NOTES:**

- A. PACKAGE REFERENCE: JEDEC TO220,ISSUE K, VARIATION AC,DATED APRIL 2002. B. ALL DIMENSIONS ARE IN MILLIMETERS. C. DIMENSION AND TOLERANCE AS PER ASME
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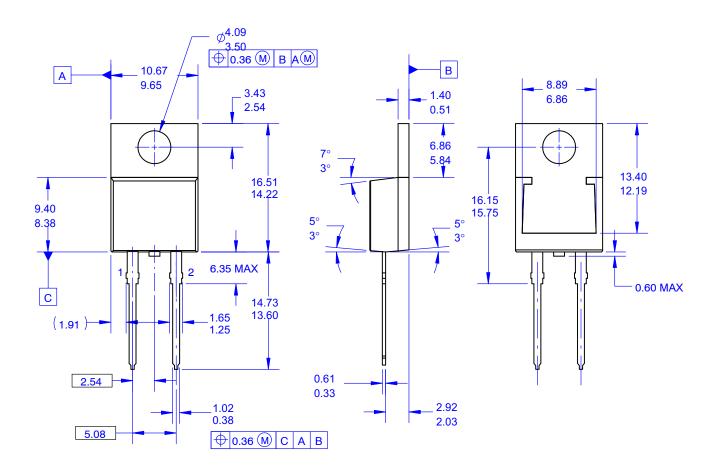
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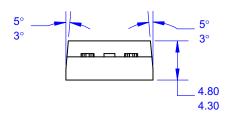
For additional information, please contact your local Sales Representative



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**DATE 31 AUG 2016** 





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